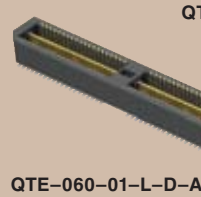




(0,80mm) .0315"

QTE SERIES



QTE-014-01-F-D-DP-A



QTE-014-01-L-D-A-RT1

# HIGH SPEED GROUND PLANE HEADER

## SPECIFICATIONS

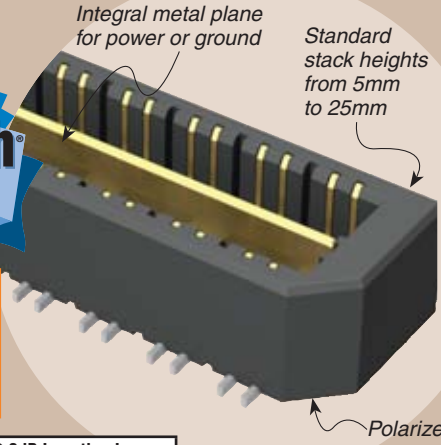
For complete specifications and recommended PCB layouts see [www.samtec.com?QTE](http://www.samtec.com?QTE)

- Insulator Material:** Liquid Crystal Polymer
- Terminal Material:** Phosphor Bronze
- Plating:** Au or Sn over 50µ" (1,27µm) Ni
- Current Rating:** Contacts: 1.3A @ 95°C  
Ground Plane: 10.1A @ 95°C
- Operating Temp Range:** -55°C to +125°C
- Voltage Rating:** 225 VAC mated with QSE & 5mm Stack Height
- Max Cycles:** 100
- Unmating Force (-RT1 option):** -RT1 option increases unmating force up to 50%
- RoHS Compliant:** Yes

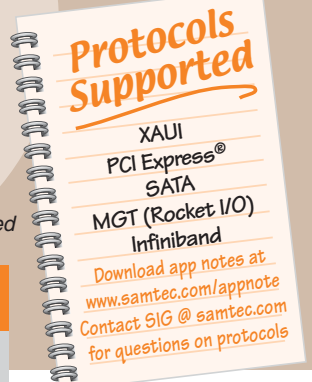


**Board Mates:** QSE

**Cable Mates:** EQCD, EQSD, EQDP, EQRF (See Application Specific note)



- E.L.P.™ plating option (-C)
- Retention pin option



5mm Stack Height	Type	Rated @ 3dB Insertion Loss
Single-Ended Signaling	-D	9 GHz / 18 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps
Differential Pair Signaling	-DP	8.5 GHz / 17 Gbps

Performance data for other stack heights and complete test data available at [www.samtec.com?QTE](http://www.samtec.com?QTE) or contact [sig@samtec.com](mailto:sig@samtec.com)

**ALSO AVAILABLE**

Board Spacing Standoffs. See SO Series.

## Processing:

- Lead-Free Solderable:** Yes
- SMT Lead Coplanarity:** (0,10mm) .004" max (020-060) (0,15mm) .006" max (080)
- Board Stacking:** For applications requiring more than two connectors per board or 4 banks or more, contact [ipg@samtec.com](mailto:ipg@samtec.com)

## APPLICATION SPECIFIC OPTION

- 14mm, 15mm, 22mm and 30mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76µm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount
- 100 positions per row
- Guide Posts, Screw Down & Friction Lock
- Call Samtec.

\*Note: -C Plating passes 10 year MFG testing  
Note: Some lengths, styles and options are non-standard, non-returnable.

QTE	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-020, -040, -060, -080 (40 total pins per bank = -D)	Specify LEAD STYLE from chart	-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails	-D = Single-Ended	-D-DP = Differential Pair (-01 only)	-K = (7,00mm) .275" DIA Polyimide Film Pick & Place Pad
	-014, -028, -042, -056 (14 pairs per bank = -D-DP)		-L = 10µ" (0,25µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails			-TR = Tape & Reel Packaging (N/A on 56 & 80 positions)
			-C* = Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails			-RT1 = Retention Option (-01 Lead Style only) (N/A on 56 & 80 positions or -L (latch) option)
						-L = Latching Option (N/A on 42, 56, 60 & 80 positions or -RT1 option)

QTE LEAD STYLE	A	HEIGHT WITH QSE*
-01	(4,27) .168	(5,00) .197
-02	(7,26) .286	(8,00) .315
-03	(10,27) .404	(11,00) .433
-04	(15,25) .600	(16,00) .630
-05	(18,26) .718	(19,00) .748
-07	(24,24) .954	(25,00) .984

\*Processing conditions will affect mated height.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)